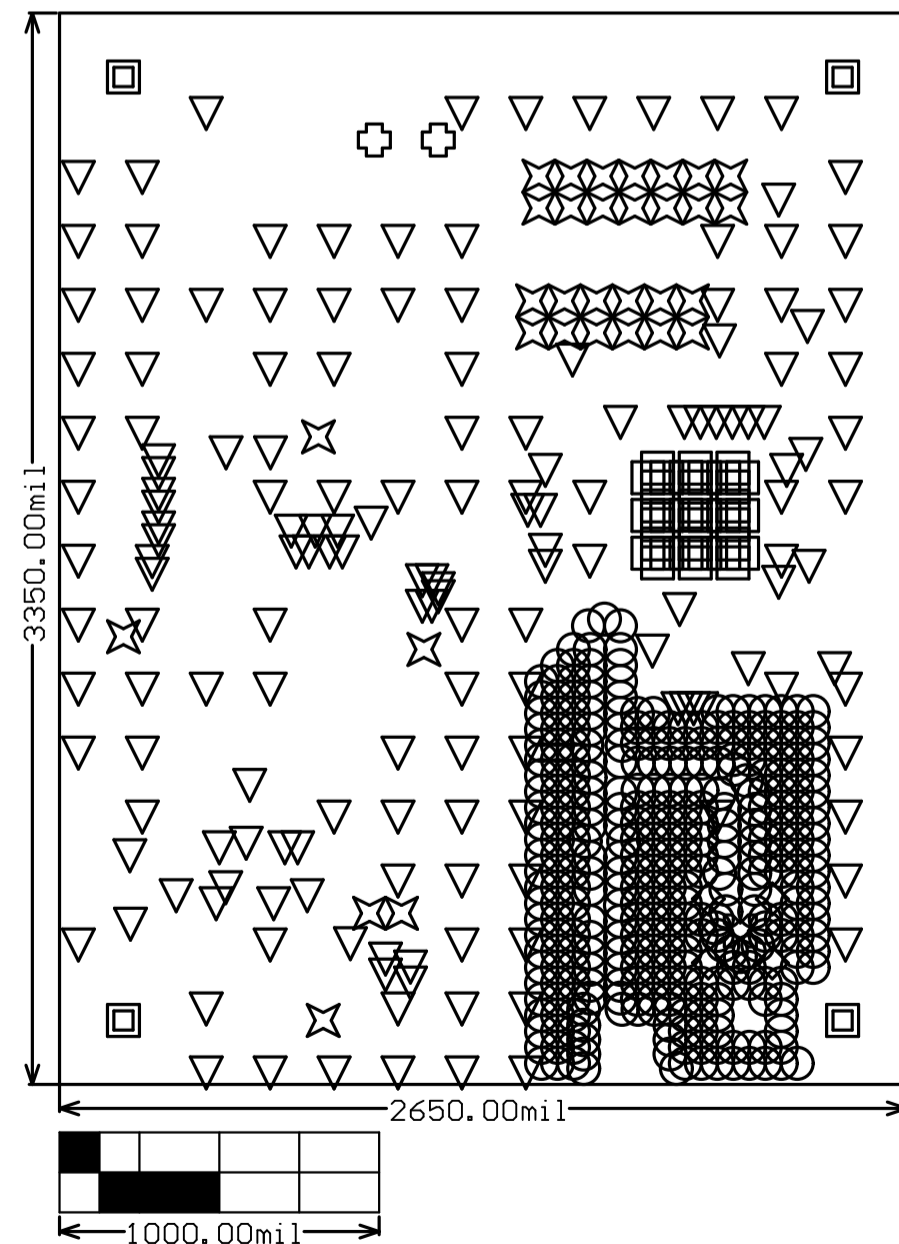


Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4 High TG	10.00mil	4.8	
5	Mid-Layer 1	Copper	1.40mil		
6	Dielectric2	FR-4 High TG	27.00mil	4.8	
7	Mid-Layer 2	Copper	1.40mil		
8	Dielectric3	FR-4 High TG	10.00mil	4.8	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

PCB IMPEDANCE CONTROL NOTE:
TOP LAYER CONTAINS 50 OHM SINGLE ENDED
TRACES USING 18MIL LINES

DESIGN INFORMATION	
MIN. TRACK WIDTH:	10 MIL
MIN. CLEARANCE:	8 MIL
MIN. VIA PAD SIZE:	18 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL PER IPC-D-275 CLASS 2 LEVEL C	
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL	
MATERIAL:	
<input type="checkbox"/> FR-408 <input checked="" type="checkbox"/> FR-4 High Tg <input type="checkbox"/> OTHER _____	
THICKNESS:	<input type="checkbox"/> 62 MIL (1.6mm) +/-10% <input checked="" type="checkbox"/> OTHER 53MIL
TOLERANCE:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2 <input type="checkbox"/> OTHER +/- _____
BOW & TWIST:	<input checked="" type="checkbox"/> ANSI IPC-6012 TYPE 3 CLASS 2 <input type="checkbox"/> OTHER +/- _____
DRILLING:	
REFERENCE:	<input checked="" type="checkbox"/> AS SHOWN <input checked="" type="checkbox"/> NC_DRILL FILES
PTH MIN COPPER THICKNESS:	<input checked="" type="checkbox"/> 1MIL <input type="checkbox"/> OTHER _____
BOARD FINISH:	
SILKSCREEN:	<input checked="" type="checkbox"/> TOP <input checked="" type="checkbox"/> BOTTOM
SILKSCREEN COLOR:	<input checked="" type="checkbox"/> WHITE <input type="checkbox"/> OTHER _____
SOLDER RESIST COLOR:	
<input checked="" type="checkbox"/> GREEN <input type="checkbox"/> BLUE <input type="checkbox"/> OTHER _____	
SURFACE FINISH:	
<input checked="" type="checkbox"/> IMMERSION GOLD (ENIG) <input type="checkbox"/> ENEPIG <input type="checkbox"/> IMM. TIN/SILVER OR EQUIV <input type="checkbox"/> OTHER _____	
ARRAY/PANEL:	
<input type="checkbox"/> CUT AND TRIM PER MECH LAYER 1 <input type="checkbox"/> N.C. ROUTE <input checked="" type="checkbox"/> V. SCORE	
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:	
<input checked="" type="checkbox"/> ANSI IPC-A-600F CLASS --> <input type="checkbox"/> 1 <input checked="" type="checkbox"/> 2 <input type="checkbox"/> 3 <input checked="" type="checkbox"/> UL 94V-0 <input checked="" type="checkbox"/> RoHS <input type="checkbox"/> OTHER PER ORDER	
ADDITIONAL REQUIREMENTS:	
MICROSECTION: <input type="checkbox"/> YES	
BARE BOARD ELEC. TEST: <input type="checkbox"/> NONE <input checked="" type="checkbox"/> REQUIRED <input type="checkbox"/> PER ORDER	
MANUFACTURER'S UL: <input type="checkbox"/> RAIL <input type="checkbox"/> METAL <input checked="" type="checkbox"/> SILK	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
□	36	7.87mil (0.200mm)	PTH	Round
○	353	8.00mil (0.203mm)	PTH	Round
▽	167	10.00mil (0.254mm)	PTH	Round
⊗	32	40.00mil (1.016mm)	PTH	Round
⊙	2	55.12mil (1.400mm)	PTH	Round
⊗	1	59.06mil (1.500mm)	PTH	Round
◇	4	62.99mil (1.600mm)	PTH	Round
■	4	125.98mil (3.200mm)	PTH	Round
	599 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE-4031	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = 0005-01-01-01	TIDA-00375		
PLOT NAME = Fabrication Drawing	GENERATED : 4/9/2015 2:59:40 PM	TEXAS INSTRUMENTS	

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ENGINEER: M. Knapp	LAYOUT BY: Krypton Solutions/RS
SCALE: 1.00	ALTIUM DESIGNER VERSION: 14.3.17.42447

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